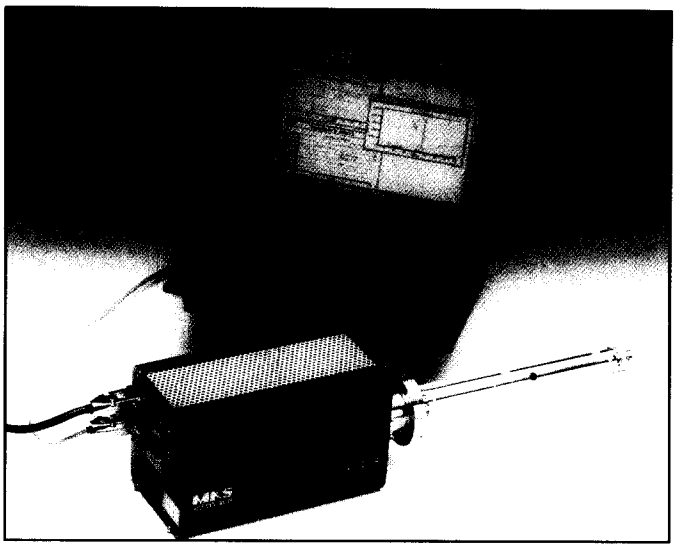


Residual process gas analysis

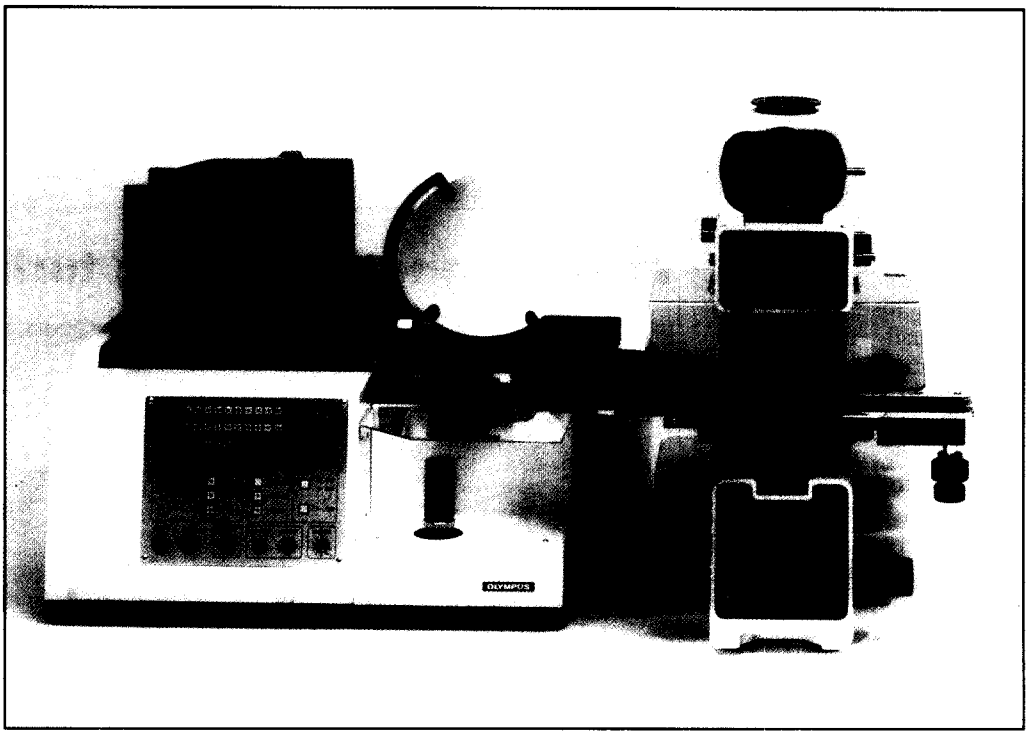
The PPT series of RGAs from MKS Instruments features a compact, cost effective analyser and is available in mass ranges up to 300 atomic mass units (AMU).

The compact PPT is controlled directly by a personal computer allowing day to day data logging of the process environment.

Process monitoring applications include monitoring oxidising/reducing atmospheres and monitoring the levels of outgassed gaseous species. In addition, the RGAs can be used for system leak detectors, containment and contamination detection and background analysis of residual gases.

■ *Contact: Andrew Dixon, MKS Instruments, UK Ltd, 2 St. Georges Court, Hanover Business Park, Dairy-house Lane, Altrincham, WA14 5UA, UK. Tel/fax: [44] (0) 161 929 5500/5511.*

Strain-free wafer inspection



A sophisticated new inspection system, the MX50, has been developed by Olympus for the repeated high magnification study required in semiconductor manufacturing. The system includes a new frame design and control positioning to improve posture and comfort for long periods of inspection, combined with revolutionary UIS optics to give brighter images with better contrast.

The Frontal Control operating system allows the user to reach and adjust controls, hour after hour, without muscle strain. Focusing knobs, illumination instensity controls, magnification change switches, and stage handles are all positioned on the front of the system. User studies have shown that this provides greater comfort and improves posture. The low controls can be adjusted without raising arms and wrists from the work surface.

A tilting observation tube, which can be inclined from 0° to 35°, allows users to match the eyepoint positioning to their height. The eyepoint can also be raised a further 30 mm. The eyepoint is 290 mm forward of the optical axis so that the operator can view specimens without straining neck and shoulder muscles.

A single set of universal objectives are provided for observation in brightfield, darkfield, Nomarski DIC and polarized light with rapid changeover between methods. Ultra-high magnification 150x and 250x objectives have been developed for the MX50 with extended working distances of 1.0 mm and 0.8 mm to prevent wafer damage.

Olympus has developed the AL100 Series wafer loaders in tandem with the MX50 to give a complete inspection system. The MX50 has an extremely small footprint of 280 x 523 mm. In combination with the AL100 wafer loader the installation space required is just 635 x 615 mm.

■ *Contact: Simon Shelley, Olympus Optical Company (UK) Ltd, 208 Honduras Street, London EC1Y OTX, UK. Tel: [44] (0) 171 2532772/6330.*